



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Patent Application of: Joseph E. Geusic et al.

Title: **INTEGRATED CIRCUITS USING OPTICAL FIBER INTERCONNECTS FORMED THROUGH A SEMICONDUCTOR WAFER**

Attorney Docket No.: 303.390US4

Customer No.: 21186

PATENT APPLICATION TRANSMITTAL

MAIL STOP PATENT APPLICATION

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items and information (as indicated with an "X"):

- ☒ Return postcard.
- ☒ **DIVISIONAL** of prior Patent Application No.(09/650569) (under 37 CFR 1.53(b)) comprising:
 - ☒ Specification (22 pgs, including claims numbered 1 through 47 and a 1 page Abstract).
 - ☒ Formal Drawing(s) (4 sheets)
 - ☒ Copy of signed Declaration (2 pgs) from prior application.
 - ☒ Copy of Power of Attorney from prior application (1 pgs).
 - ☒ Incorporation by Reference: *The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied herewith, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.*
- ☒ Check in the amount of \$1600.00 to pay the filing fee.
- ☒ Prior application is assigned of record to Micron Technology, Inc..
- ☒ Information Disclosure Statement (2 pgs), Form 1449 (4 pgs)
References NOT enclosed, cited in prior application.
- ☒ A Communication Concerning Related Applications (2 pgs.).

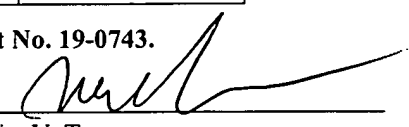
The filing fee has been calculated below as follows:

	No. Filed	No. Extra	Rate	Fee
TOTAL CLAIMS	47-20	27	x 18.00 =	\$486.00
INDEPENDENT CLAIMS	7-3	4	x 86.00 =	\$344.00
[] MULTIPLE DEPENDENT CLAIMS PRESENTED				\$0.00
BASIC FEE				\$770.00
TOTAL				\$1600.00

Please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

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S/N Unknown

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Joseph E. Geusic et al. Examiner: Unknown
Serial No.: Unknown Group Art Unit: Unknown
Filed: Herewith Docket: 303.390US4
Title: INTEGRATED CIRCUITS USING OPTICAL FIBER INTERCONNECTS
FORMED THROUGH A SEMICONDUCTOR WAFER

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/031961 6090636	February 26, 1998	303.382US1	INTEGRATED CIRCUITS USING OPTICAL WAVEGUIDE INTERCONNECTS FORMED THROUGH A SEMICONDUCTOR WAFER AND METHODS FOR FORMING SAME
09/618648	July 18, 2000	303.382US2	INTEGRATED CIRCUITS USING OPTICAL WAVEGUIDE INTERCONNECTS FORMED THROUGH A SEMICONDUCTOR WAFER AND METHODS FOR FORMING SAME
09/009791 6198168	January 20, 1998	303.388US1	INTEGRATED CIRCUITS USING HIGH ASPECT RATIO VIAS THROUGH A SEMICONDUCTOR WAFER AND METHOD FOR FORMING SAME
09/800373	March 6, 2001	303.388US2	INTEGRATED CIRCUITS USING HIGH ASPECT RATIO VIAS THROUGH A SEMICONDUCTOR WAFER AND METHOD FOR FORMING SAME

COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: Unknown

Filing Date: Herewith

Title: METHOD OF FORMING AN OPTICAL FIBER INTERCONNECT THROUGH A SEMICONDUCTOR WAFER

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09/642960 6526191	August 21, 2000	303.390US2	INTEGRATED CIRCUITS USING OPTICAL FIBER INTERCONNECTS FORMED THROUGH A SEMICONDUCTOR WAFER AND METHODS FOR FORMING SAME
10/435172	May 8, 2003	303.382US3	INTEGRATED CIRCUITS USING OPTICAL WAVEGUIDE INTERCONNECTS FORMED THROUGH A SEMICONDUCTOR WAFER AND METHODS FOR FORMING SAME

Respectfully submitted,

JOSEPH E. GEUSIC ET AL.

By Applicants' Representatives,

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